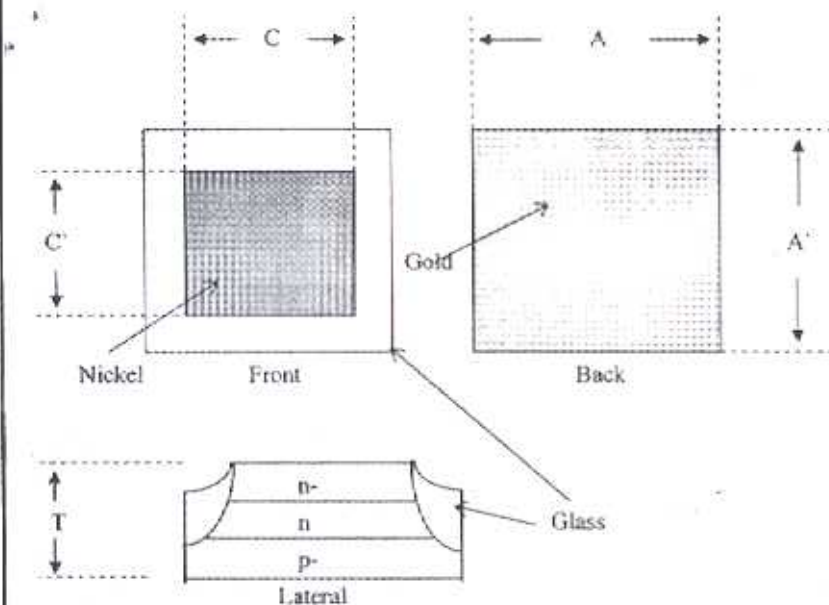


Chip Dimension	120 X 120 mil	Customer:	Wetherill Associates Inc	Part Number :	PBAGPP120
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A. Dimension , Outward :



	A	A'	C	C'	T
mil	120 ± 2	120 ± 2	95 ± 2	95 ± 2	9 ± 1
mm	3.05 ± 0.05	3.05 ± 0.05	2.41 ± 0.05	2.41 ± 0.05	0.23 ± 0.03

B. Silicon Die Electrical Test :

100 Die From Every Lot Test By Microscope.

$V_f \geq 500V \geq 95\%$, sharp $\geq 80\%$ to determine Accept.

C. Silicon Die Outward Inspection :

Critical Defects (CR) - 105D(form) , LEVEL II , 0.025

Major Defects (MA) - 105D(form) , LEVEL II , 0.15

Minor Defects (MI) - 105D(form) , LEVEL II , 0.65

D. Assembly Silicon Die Electrical Test :

Assembly to Dish or Axial lead Diode, Use TVS-168 Tester

Software item "120mil in" test electrical reading.

	$V_f (V)$	$I_r (\mu A)$	$V_f (V)$	$T_{rr} (nS)$
	$I_r = 5 \mu A$	$V_r = 400V$	$I_F = 6A$	
Customer Spec.	>400	≤ 2	<0.98	---
Setting Spec.	≥ 500	≤ 1	≤ 0.97	≥ 1200

97% According to Setting Spec. Will determine Accept.

CPM: 18100

Conclude in accordance with :

F89051701 Engineering communication form.

Product :	QC Dept. :	Issue By:	J. Yang	Date :	11/9/2001
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